

(0.635 mm) .025"

MIS SERIES

# MIXED TECHNOLOGY SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MIS](http://www.samtec.com?MIS)

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50 μ" (1.27 μm) Ni
- Operating Temp Range:** -55 °C to +125 °C
- Voltage Rating:** 275 VAC
- Max Cycles:** 100
- RoHS Compliant:** Yes

## PROCESSING

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0.10 mm) .004" max (019-057)
- Board Stacking:** For applications requiring more than two connectors per board contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



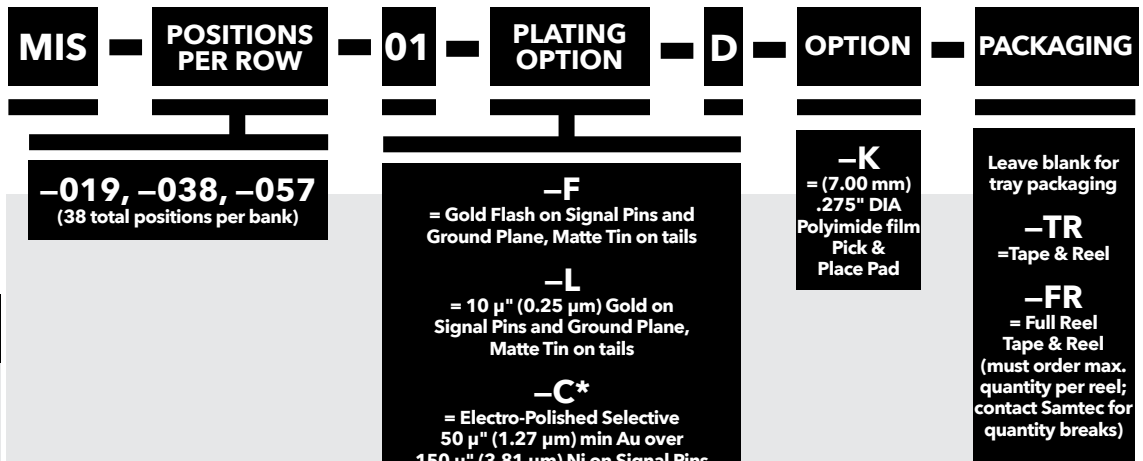
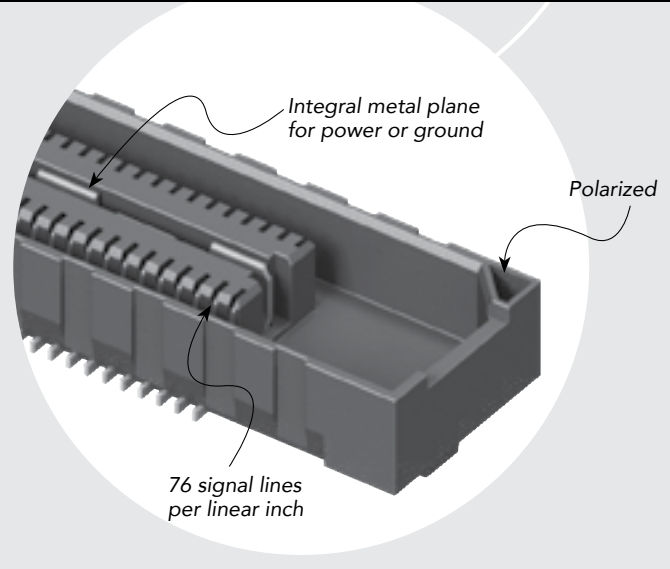
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## ALSO AVAILABLE (MOQ Required)

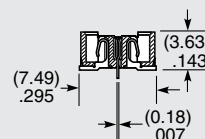
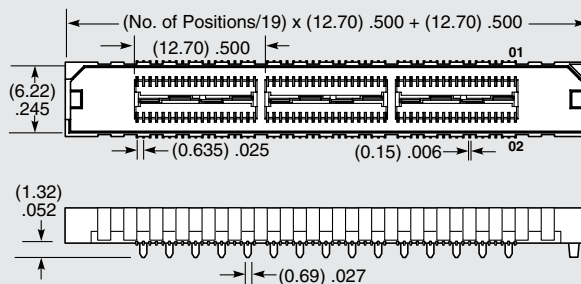
- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

**Board Mates:** MIT

**Standoffs:** SO



**\*Note:**  
-C Plating passes 10 year MFG testing



**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
	-01	-02
-01	(5.00) .197	(8.00) .315

\*Processing conditions will affect mated height. See SO Series for board space tolerances.

**Note:** Some lengths, styles and options are non-standard, non-returnable.